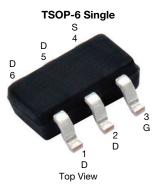


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# Automotive N-Channel 60 V (D-S) 175 °C MOSFET



Marking Code: 9Hxxx

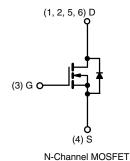
| PRODUCT SUMMARY                                  |        |  |  |  |  |
|--|--------|--|--|--|--|
| V <sub>DS</sub> (V)                              | 60     |  |  |  |  |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$  | 0.042  |  |  |  |  |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$ | 0.063  |  |  |  |  |
| I <sub>D</sub> (A)                               | 7      |  |  |  |  |
| Configuration                                    | Single |  |  |  |  |

#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>q</sub> and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



ROHS COMPLIANT HALOGEN FREE



| ORDERING INFORMATION            |   |
|---------------------------------|---|
| Package                         | TSOP-6  |
| Lead (Pb)-free and halogen-free | SQ3426CEV (for detailed order number please see <a href="https://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> ) |

| PARAMETER  |                         | SYMBOL                            | LIMIT       | UNIT |  |
|--|-------------------------|-----------------------------------|-------------|------|--|
| Drain-source voltage                             |                         | $V_{DS}$                          | 60          | V    |  |
| Gate-source voltage                              |                         | $V_{GS}$                          | ± 20        | V    |  |
| Continuous drain current                         | T <sub>C</sub> = 25 °C  | 1                                 | 7           | А    |  |
|  | T <sub>C</sub> = 125 °C | I <sub>D</sub>                    | 4           |      |  |
| Continuous source current (diode conduct         | ion)                    | I <sub>S</sub>                    | 6           |      |  |
| Pulsed drain current <sup>a</sup>                |                         | I <sub>DM</sub>                   | 29          |      |  |
| Single pulse avalanche current                   | L = 0.1 mH              | I <sub>AS</sub>                   | 10          |      |  |
| Single pulse avalanche energy                    | L = U.I IIII            | E <sub>AS</sub>                   | 5           | mJ   |  |
| Maximum power dissipation                        | T <sub>C</sub> = 25 °C  | В                                 | 5           | W    |  |
|  | T <sub>C</sub> = 125 °C | $P_{D}$                           | 1.6         | VV   |  |
| Operating junction and storage temperature range |                         | T <sub>J</sub> , T <sub>stq</sub> | -55 to +175 | °C   |  |

| THERMAL RESISTANCE RATINGS |             |            |      |      |  |  |
|----------------------------|-------------|------------|------|------|--|--|
| PARAMETER                  | SYMBOL      | LIMIT      | UNIT |      |  |  |
| Junction to ambient        | PCB mount b | $R_{thJA}$ | 110  | °C/W |  |  |
| Junction to foot (drain)   |             | $R_{thJF}$ | 30   | C/VV |  |  |

#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. When mounted on 1" square PCB (FR4 material)



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| PARAMETER                                | SYMBOL                 | TES   | MIN.  | TYP. | MAX.  | UNIT  |      |  |
|--|------------------------|---|---|------|-------|-------|------|--|
| Static                                   |                        |   |   |      |       |       |      |  |
| Drain-source breakdown voltage           | V <sub>DS</sub>        | $V_{GS} = 0$ , $I_D = 250 \mu A$  |   | 60   | -     | -     |      |  |
| Gate-source threshold voltage            | V <sub>GS(th)</sub>    | $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$  |   | 1.5  | 2     | 2.5   | V    |  |
| Cata agura laglaga                       |                        | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$   |   | -    | -     | ± 100 | - nA |  |
| Gate-source leakage                      | I <sub>GSS</sub>       | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$   |   |      | -     | ± 300 |      |  |
|  |                        | $V_{GS} = 0 V$  | V <sub>DS</sub> = 60 V                          | =.   | -     | 1     |      |  |
| Zero gate voltage drain current          | I <sub>DSS</sub>       | V <sub>GS</sub> = 0 V   | V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C | =-   | -     | 50    | μΑ   |  |
|  |                        | V <sub>GS</sub> = 0 V   | V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C | -    | -     | 150   |      |  |
| On-state drain current <sup>a</sup>      | I <sub>D(on)</sub>     | V <sub>GS</sub> = 10 V  | $V_{DS} \ge 5 V$                                | 10   | -     | -     | Α    |  |
|  |                        | V <sub>GS</sub> = 10 V  | I <sub>D</sub> = 5 A                            | -    | 0.034 | 0.042 | Ω    |  |
| Duning and the projection of a           |                        | V <sub>GS</sub> = 10 V  | I <sub>D</sub> = 5 A, T <sub>J</sub> = 125 °C   | -    | -     | 0.073 |      |  |
| Drain-source on-state resistance a       | R <sub>DS(on)</sub>    | V <sub>GS</sub> = 10 V  | I <sub>D</sub> = 5 A, T <sub>J</sub> = 175 °C   | -    | -     | 0.092 |      |  |
|  |                        | V <sub>GS</sub> = 4.5 V   | I <sub>D</sub> = 4 A                            | -    | 0.037 | 0.063 |      |  |
| Forward transconductance a               | 9 <sub>fs</sub>        | V <sub>DS</sub>   | = 15 V, I <sub>D</sub> = 4 A                    | -    | 21    | -     | S    |  |
| Dynamic <sup>b</sup>                     |                        |   |   |      |       |       |      |  |
| Input Capacitance                        | C <sub>iss</sub>       |   |   | -    | 718   | 790   |      |  |
| Output Capacitance                       | C <sub>oss</sub>       | $V_{GS} = 0 V$  | $V_{DS} = 30 \text{ V, f} = 1 \text{ MHz}$      | -    | 75    | 110   | рF   |  |
| Reverse Transfer Capacitance             | C <sub>rss</sub>       |   |   | -    | 29    | 70    |      |  |
| Total Gate Charge <sup>c</sup>           | $Q_g$                  |   |   | -    | 6.8   | 12    |      |  |
| Gate-Source Charge c                     | Q <sub>gs</sub>        | $V_{GS} = 4.5 \text{ V}$  | $V_{DS} = 30 \text{ V}, I_{D} = 4 \text{ A}$    | =.   | 2.9   | -     | nC   |  |
| Gate-Drain Charge <sup>c</sup>           | $Q_{gd}$               |   |   | -    | 2.0   | -     |      |  |
| Gate Resistance                          | $R_g$                  | f = 1 MHz   |   | 1.9  | 3.1   | 5.7   | Ω    |  |
| Turn-On Delay Time <sup>c</sup>          | t <sub>d(on)</sub>     |   |   |      | 9     | 14    |      |  |
| Rise Time <sup>c</sup>                   | t <sub>r</sub>         | $V_{DD} = 30 \text{ V}, \text{ R}_{L} = 7.5 \Omega$ $I_{D} \cong 4 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_{g} = 1 \Omega$ |   | -    | 3     | 18    | ns   |  |
| Turn-Off Delay Time <sup>c</sup>         | t <sub>d(off)</sub>    |   |   | -    | 19    | 29    |      |  |
| Fall Time <sup>c</sup>                   | t <sub>f</sub>         |   |   | =.   | 4     | 11    |      |  |
| Source-Drain Diode Ratings and Charac    | teristics <sup>b</sup> |   |   |      |       |       |      |  |
| Pulsed current <sup>a</sup>              | I <sub>SM</sub>        |   |   | -    | -     | 29    | Α    |  |
| Forward voltage                          | V <sub>SD</sub>        | I <sub>F</sub> = 1.6 A, V <sub>GS</sub> = 0 V   |   | -    | 0.77  | 1.2   | V    |  |
| Body diode reverse recovery time         | t <sub>rr</sub>        |   |   | -    | 19    | 38    | ns   |  |
| Body diode reverse recovery charge       | Q <sub>rr</sub>        | I <sub>F</sub> = 4 A, di/dt = 100 A/μs  |   | =.   | 18    | 36    | nC   |  |
| Reverse recovery fall time               | t <sub>a</sub>         |   |   | -    | 15    | -     | ns   |  |
| Reverse recovery rise time               | t <sub>b</sub>         |   |   | -    | 4     | -     |      |  |
| Body diode peak reverse recovery current | I <sub>RM(REC)</sub>   |   |   | -    | -2.1  | -     | Α    |  |

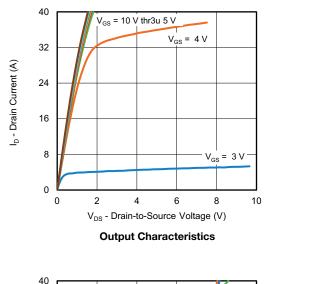
#### Notes

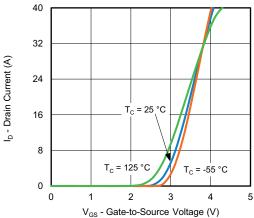
- a. Pulse test; pulse width  $\leq 300~\mu\text{s},$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

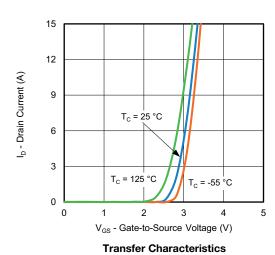


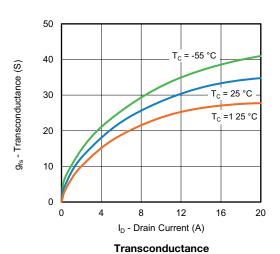
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

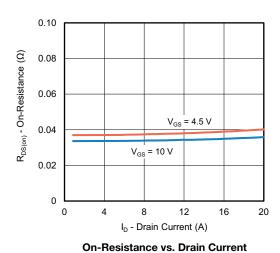


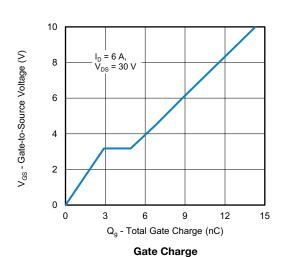


**Transfer Characteristics** 



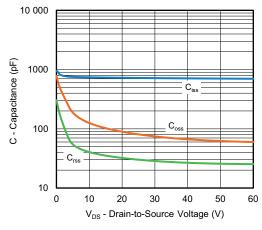




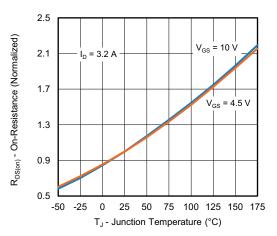




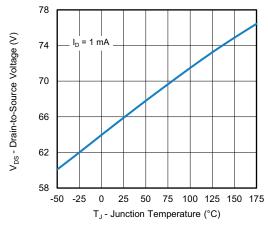
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



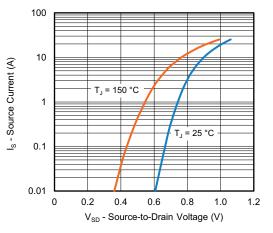
#### Capacitance



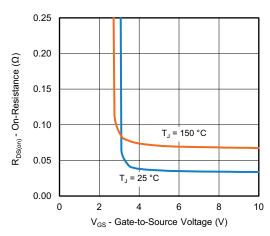
On-Resistance vs. Junction Temperature



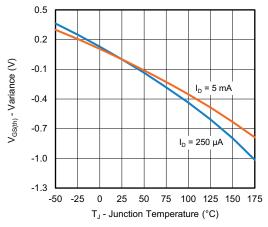
Drain Source Breakdown vs. Junction Temperature



**Source Drain Diode Forward Voltage** 



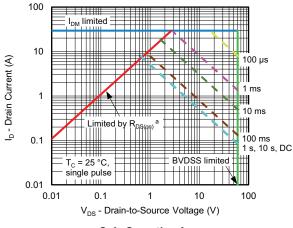
On-Resistance vs. Gate-Source Voltage



**Threshold Voltage** 



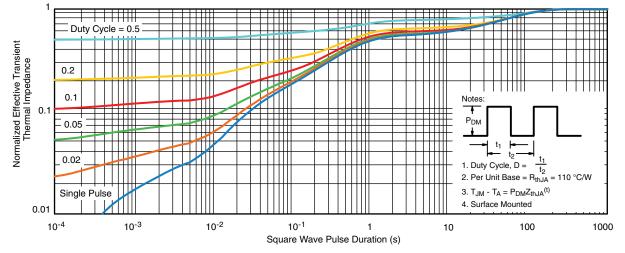
## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Safe Operating Area

#### Note

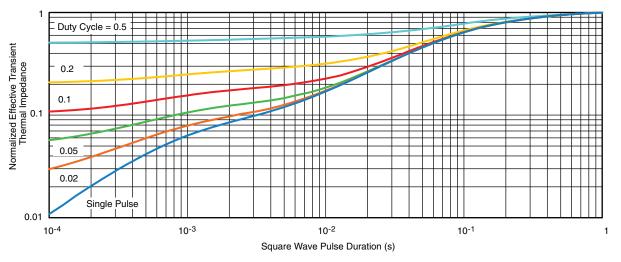
a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



Normalized Thermal Transient Impedance, Junction-to-Ambient



### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized thermal Transient Impedance, Junction-to-Foot

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

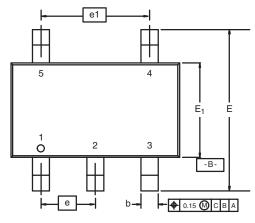
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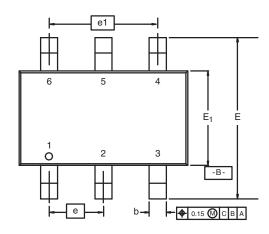




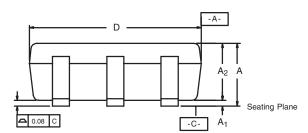
TSOP: 5/6-LEAD

**JEDEC Part Number: MO-193C** 

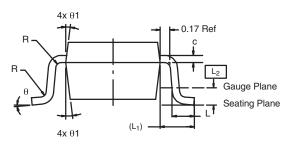




**5-LEAD TSOP** 





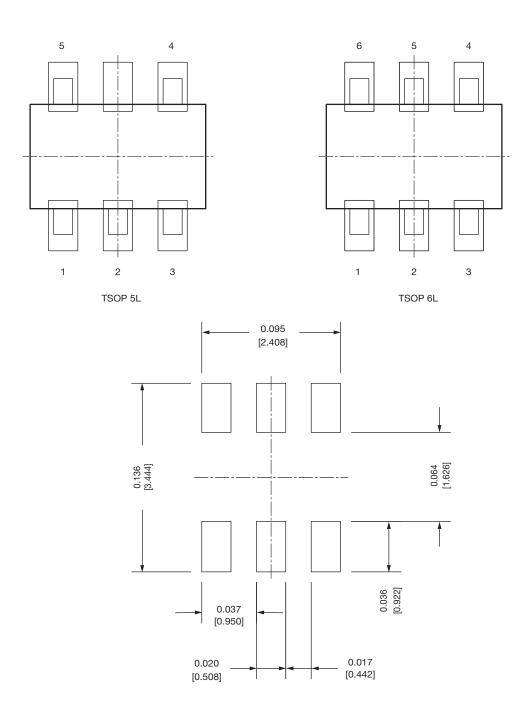


|                | MIL      | LIMETER       | RS   | INCHES     |       |       |  |
|----------------|----------|---------------|------|------------|-------|-------|--|
| Dim            | Min      | Nom           | Max  | Min        | Nom   | Max   |  |
| Α              | 0.91     | -             | 1.10 | 0.036      | -     | 0.043 |  |
| A <sub>1</sub> | 0.01     | -             | 0.10 | 0.0004     | -     | 0.004 |  |
| A <sub>2</sub> | 0.90     | -             | 1.00 | 0.035      | 0.038 | 0.039 |  |
| b              | 0.30     | 0.32          | 0.45 | 0.012      | 0.013 | 0.018 |  |
| С              | 0.10     | 0.15          | 0.20 | 0.004      | 0.006 | 0.008 |  |
| D              | 2.95     | 3.05          | 3.10 | 0.116      | 0.120 | 0.122 |  |
| E              | 2.70     | 2.85          | 2.98 | 0.106      | 0.112 | 0.117 |  |
| E <sub>1</sub> | 1.55     | 1.65          | 1.70 | 0.061      | 0.065 | 0.067 |  |
| е              |          | 0.95 BSC      |      | 0.0374 BSC |       |       |  |
| e <sub>1</sub> | 1.80     | 1.90          | 2.00 | 0.071      | 0.075 | 0.079 |  |
| L              | 0.32     | -             | 0.50 | 0.012      | -     | 0.020 |  |
| L <sub>1</sub> | 0.60 Ref |               |      | 0.024 Ref  |       |       |  |
| L <sub>2</sub> | 0.25 BSC |               |      | 0.010 BSC  |       |       |  |
| R              | 0.10     | -             | -    | 0.004      | -     | -     |  |
| θ              | 0°       | 4°            | 8°   | 0°         | 4°    | 8°    |  |
| θ1             | 7° Nom   |               |      | 7° Nom     |       |       |  |
| ECN: C         |          | ev. I, 18-Dec | c-06 |            |       |       |  |

Document Number: 71200 18-Dec-06



# Recommended Land Pattern For TSOP-5L / TSOP-6L



### Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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